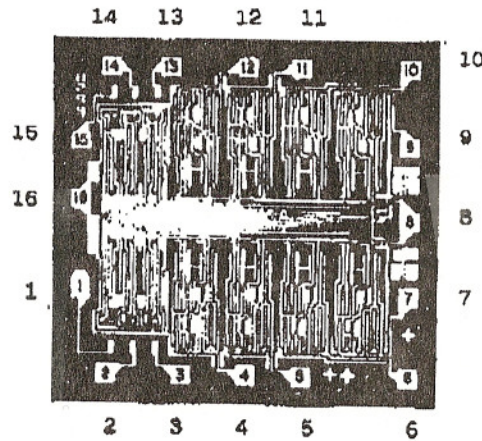




Sierra Components, Inc.

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Chip back potential is the level which bulk silicon is maintained by on-chip connection, or it is the level to which the chip back must be connected when specifically stated below. If no potential is given the chip back should be isolated.



<u>PAD NO</u>	<u>FUNCTIONS</u>
1	E
2	A
3	B
4	Q0
5	Q1
6	Q2
7	Q3
8	VSS
9	Q3
10	Q0
11	Q1
12	Q2
13	B
14	A
15	E
16	VDD

Lines from pads 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, and 16 converge to a point labeled "X OF DUAL".
 Lines from pads 1, 2, 3, 4, 5, 6, 7, 8, 9, 10, 11, 12, 13, 14, 15, and 16 converge to another point labeled "X OF DUAL".

Top Material:
Backside Material:
Bond Pad Size:
Backside Potential:
Mask Ref:

APPROVED BY:MG

DIE SIZE :83 x 79

DATE: 10/28/08

MFG:RCA

THICKNESS:

P/N:CD4556BH